

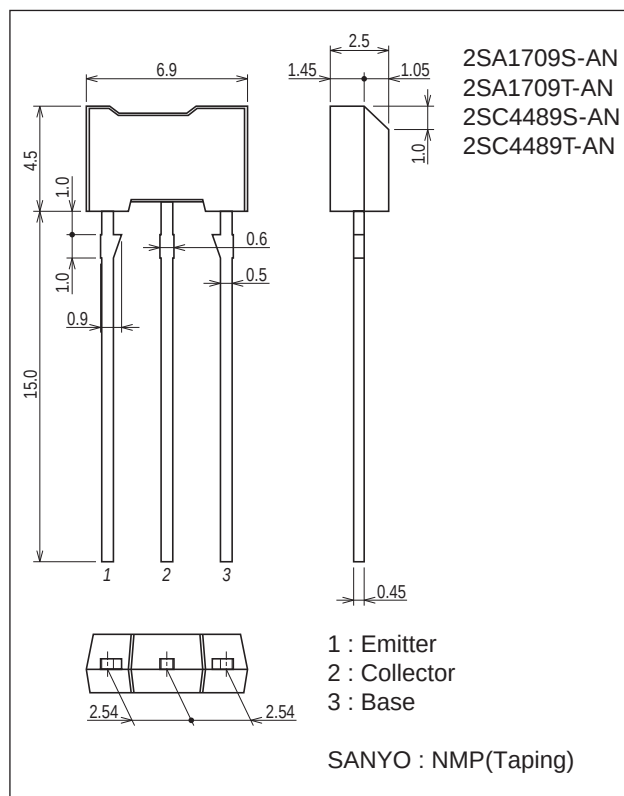
- Adoption of FBET, MBIT processes
- Fast switching speed

- High breakdown voltage, large current capacity

Specifications

Parameter	Symbol	Conditions	Ratings	Unit
Collector-to-Base Voltage	V _{CB0}		(-) 120	V
Collector-to-Emitter Voltage	V _{CEO}		(-) 100	V
Emitter-to-Base Voltage	V _{EB0}		(-) 6	V
Collector Current	I _C		(-) 2	A
Collector Current (Pulse)	I _{CP}		(-) 3	A
Collector Dissipation	P _C		1	W
Junction Temperature	T _J		150	°C
Storage Temperature	T _{stg}		-55 to +150	°C

7540-001



- Package : NMP(Taping)
- JEITA, JEDEC : SC-71
- Minimum Packing Quantity : 2,500 pcs./box

The diagram illustrates two different cable connector types, A1709 and C4489. Each connector is shown with a label and three pins. The label for A1709 has 'RANK' and 'LOT No.' fields, and the label for C4489 also has 'RANK' and 'LOT No.' fields. The pins are shown as three vertical lines extending from the bottom of each connector.

2SA1709 / 2SC4489

Electrical Characteristics at Ta=25°C

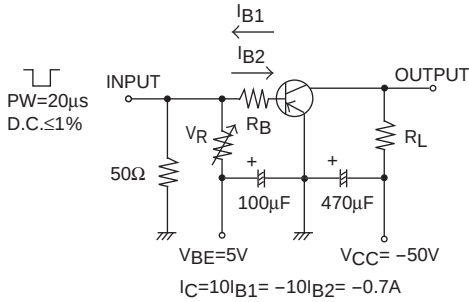
Parameter	Symbol	Conditions	Ratings			Unit
			min	typ	max	
Collector Cutoff Current	I_{CBO}	$V_{CB}=(-)100V, I_E=0A$			$(-)100$	nA
Emitter Cutoff Current	I_{EBO}	$V_{EB}=(-)4V, I_C=0A$			$(-)100$	nA
DC Current Gain	h_{FE}	$V_{CE}=(-)5V, I_C=(-)100mA$	140*		400*	
Gain-Bandwidth Product	f_T	$V_{CE}=(-)10V, I_C=(-)100mA$		120		MHz
Output Capacitance	C_{ob}	$V_{CB}=(-)10V, f=1MHz$		(25)16		pF
Collector-to-Emitter Saturation Voltage	$V_{CE(sat)}$	$I_C=(-)1A, I_B=(-)100mA$		$(-0.22)0.13$	$(-0.6)0.4$	V
Base-to-Emitter Saturation Voltage	$V_{BE(sat)}$	$I_C=(-)1A, I_B=(-)100mA$		$(-)0.85$	$(-)1.2$	V
Collector-to-Base Breakdown Voltage	$V_{(BR)CBO}$	$I_C=(-)10\mu A, I_E=0A$	$(-)120$			V
Collector-to-Emitter Breakdown Voltage	$V_{(BR)CEO}$	$I_C=(-)1mA, R_{BE}=\infty$	$(-)100$			V
Emitter-to-Base Breakdown Voltage	$V_{(BR)EBO}$	$I_E=(-)10\mu A, I_C=0A$	$(-)6$			V
Turn-On Time	t_{on}	See specified Test Circuit.		80		ns
Storage Time	t_{stg}			(750)1000		ns
Fall Time	t_f			(40)50		ns

* : The 2SA1709/2SC4489 are classified by 100mA h_{FE} as follows :

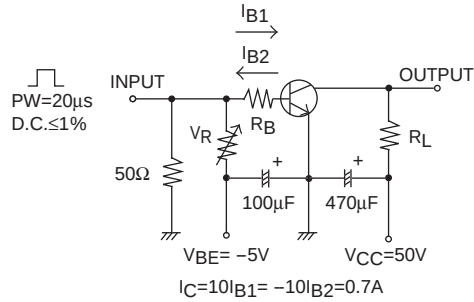
Rank	S	T
h_{FE}	140 to 280	200 to 400

Switching Time Test Circuit

2SA1709

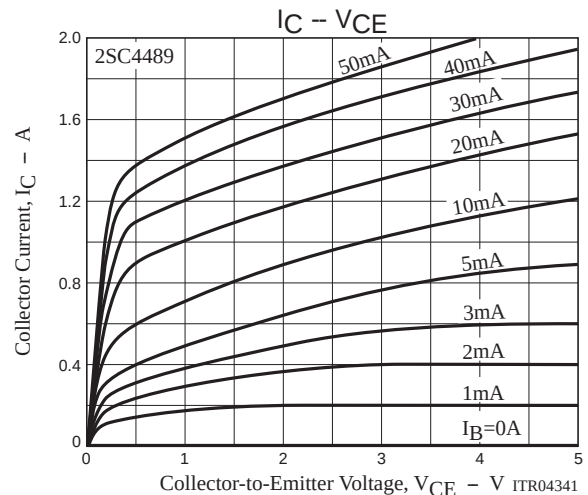
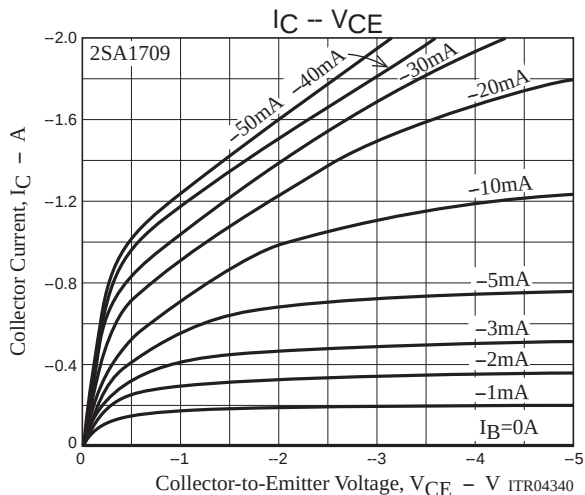


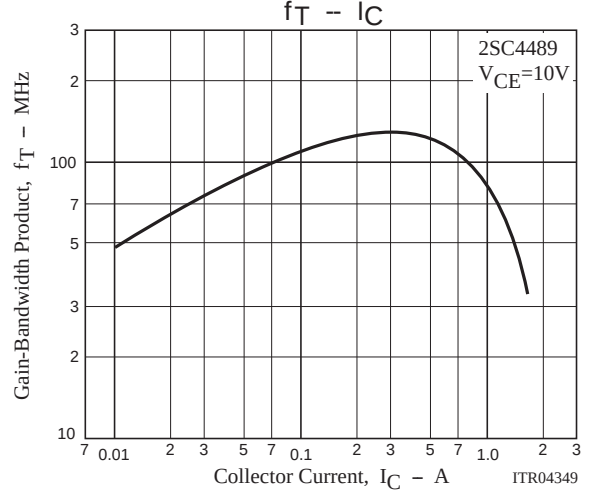
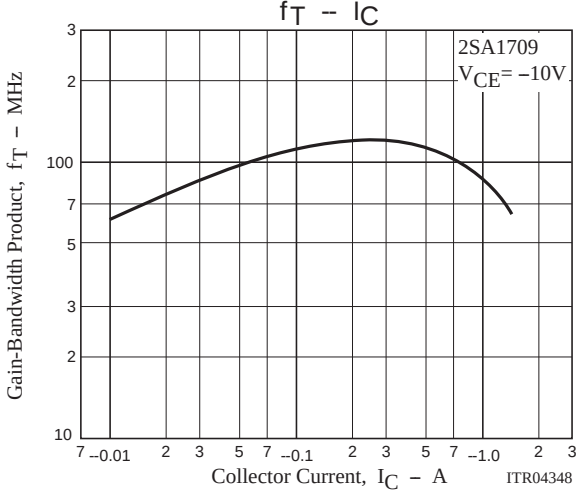
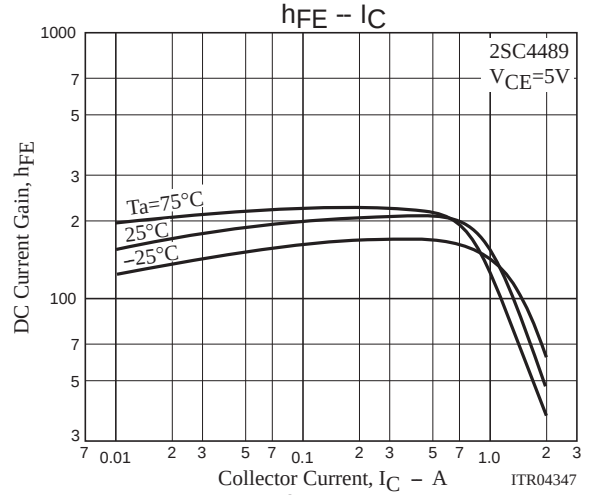
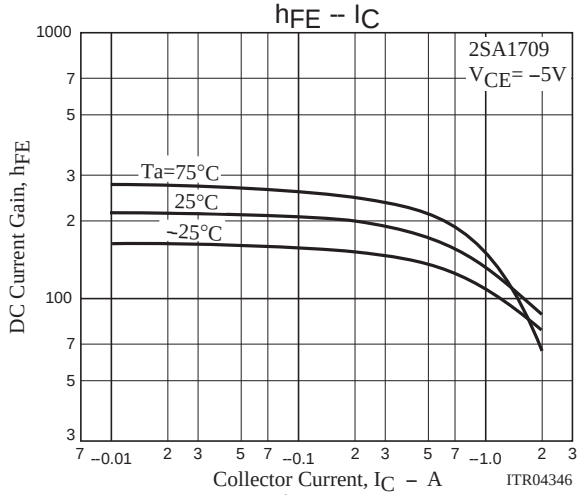
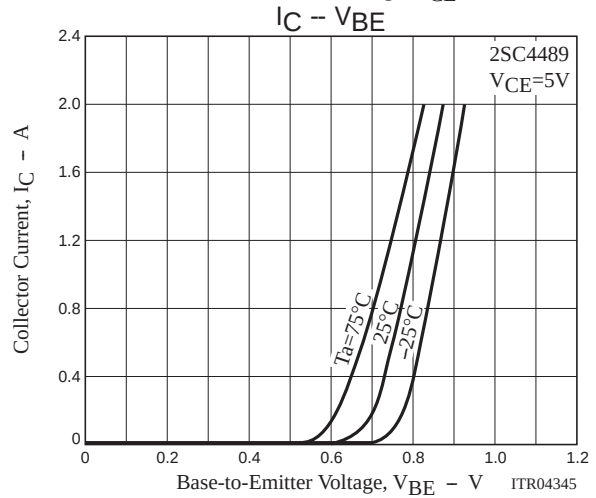
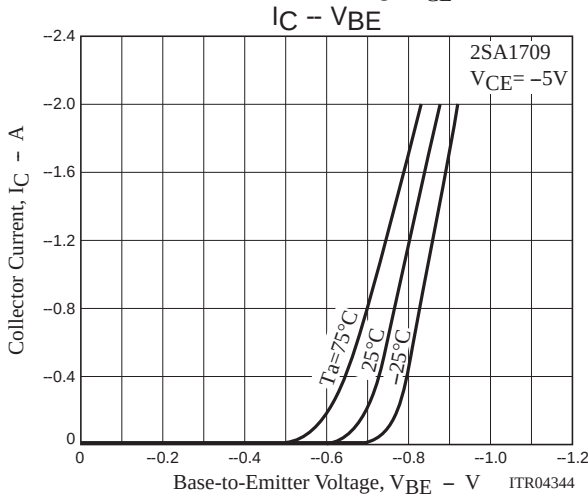
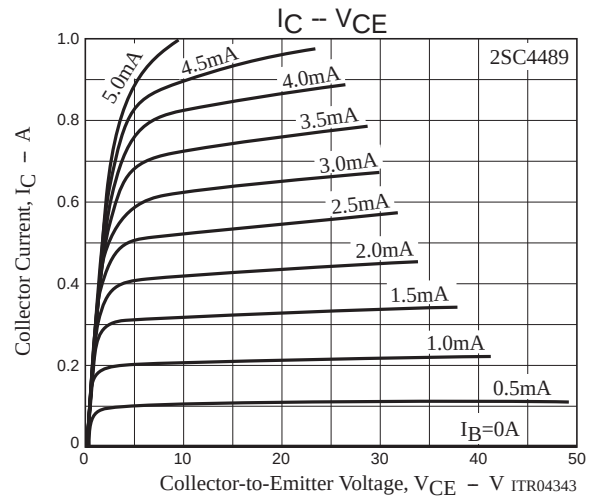
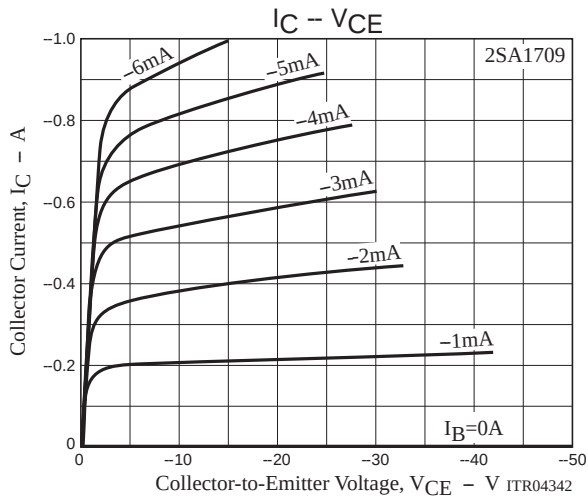
2SC4489

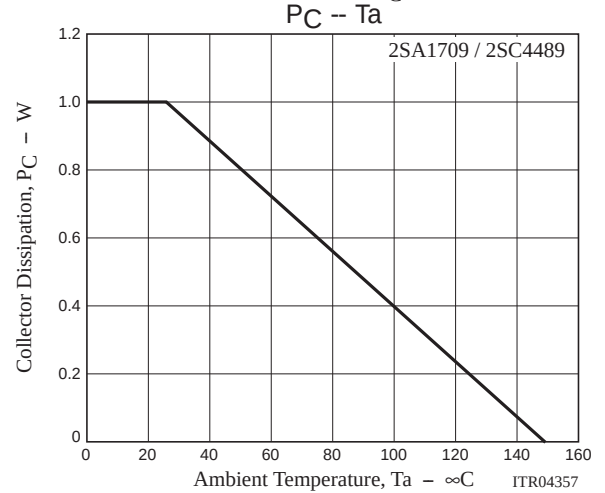
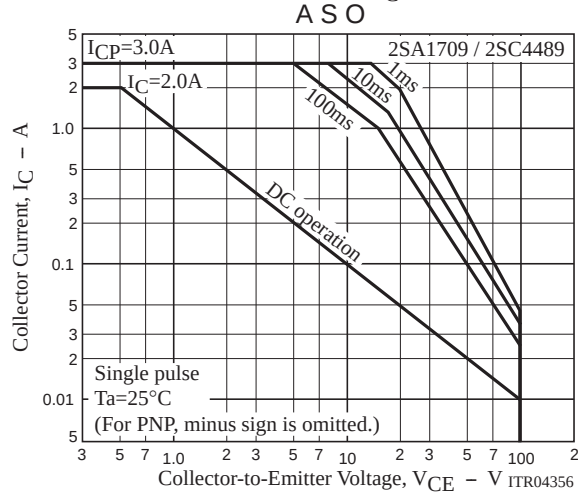
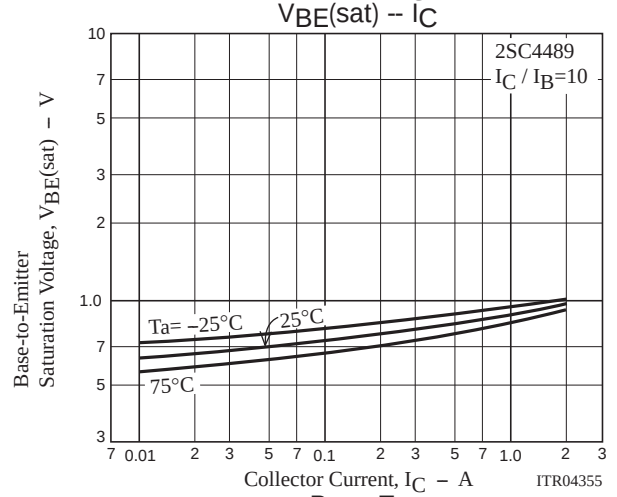
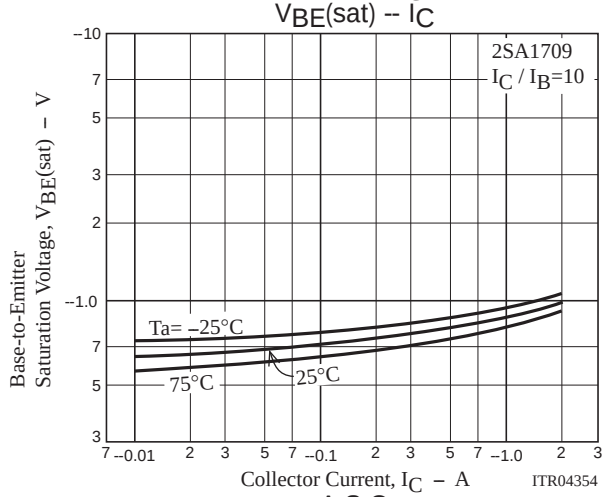
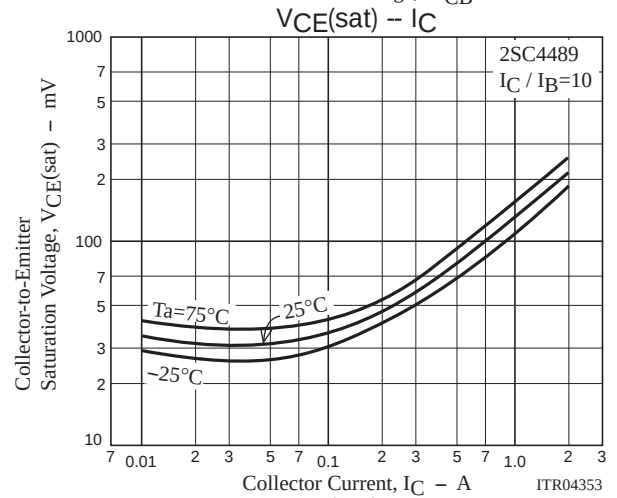
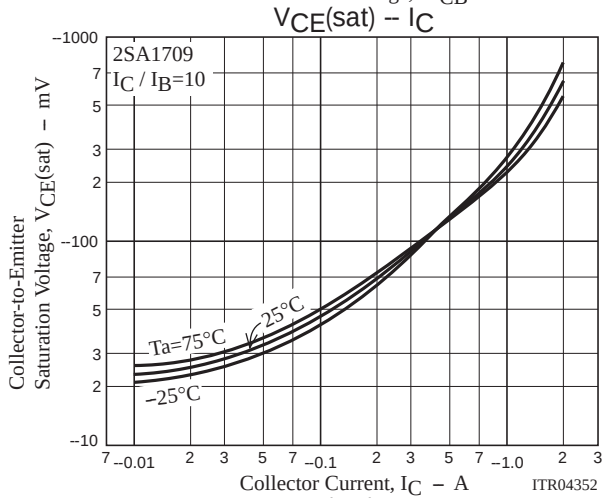
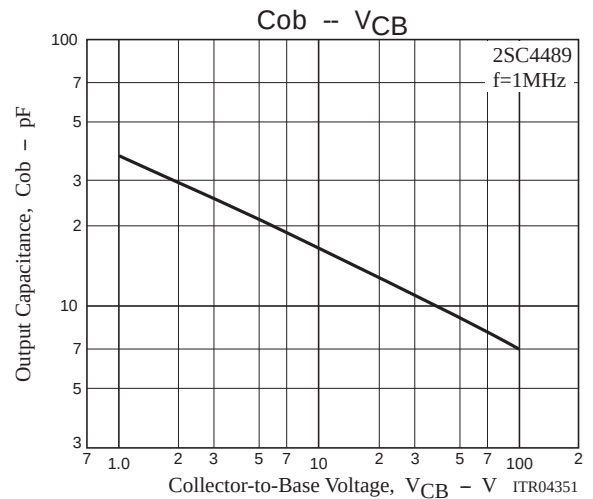
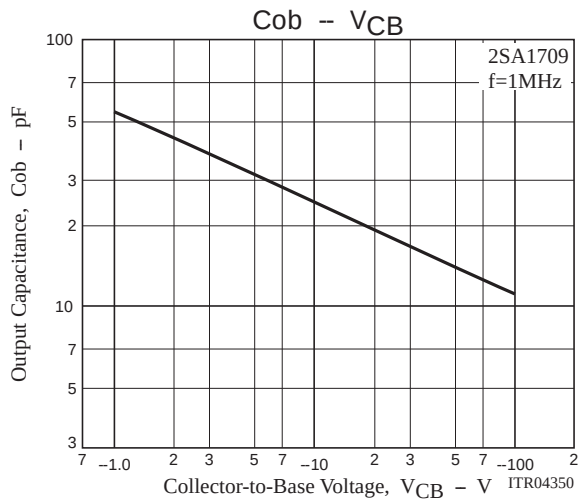


Ordering Information

Device	Package	Shipping	memo
2SA1709S-AN	NMP(Taping)	2,500pcs./bag	Pb Free
2SA1709T-AN	NMP(Taping)	2,500pcs./bag	
2SC4489S-AN	NMP(Taping)	2,500pcs./bag	
2SC4489T-AN	NMP(Taping)	2,500pcs./bag	







Bag Packing Specification

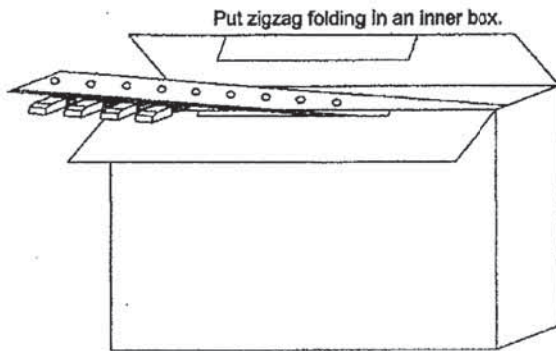
2SA1709S-AN, 2SA1709T-AN, 2SC4489S-AN, 2SC4489T-AN

NMP (Zigzag folding)

Storage package Outline name	Package type	Maximum Number of devices contained (pcs.)		Packing format	
		Inner box No.	Storage quantity	Outer box (C—6)	Outer box (C—8)
NMP	AN/AZ	C—3 Inner box Dimensions :mm(external) 330×45×125	2,500	8 inner boxes contained(20,000pcs.) Outer box Dimensions:mm(external) 585×345×195	4 inner boxes contained(10,000pcs.) Outer box Dimensions:mm(external) 345×300×195

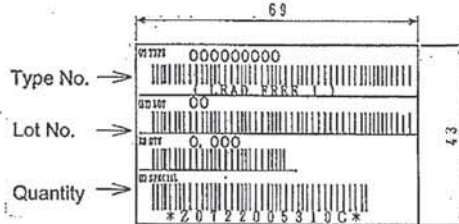
1. Packing format

Packing method



2. Bar code label

(Unit : mm)

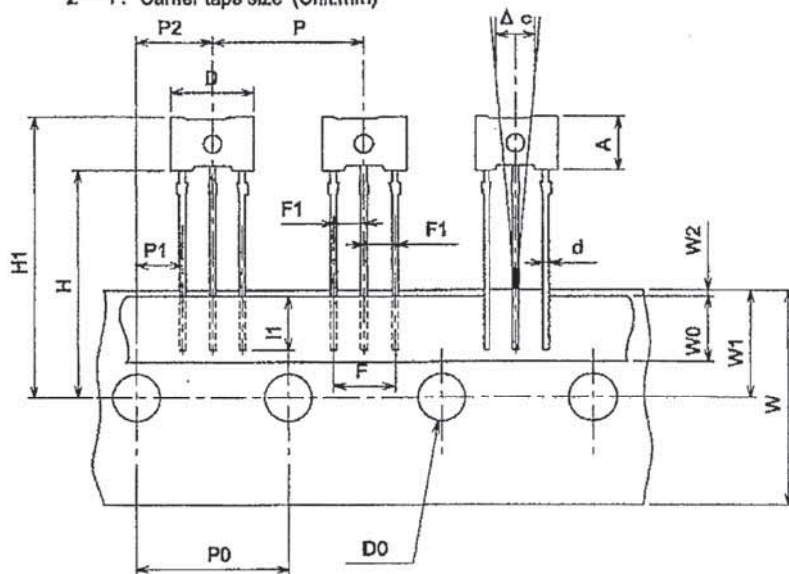


*LEAD FREE 1:

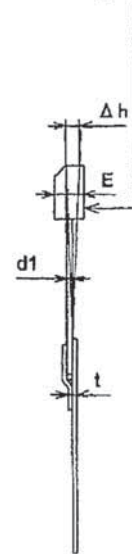
Lead-free External terminal surface treatment product.

2. Taping specifications

2—1. Carrier tape size (Unit:mm)



Marking surface

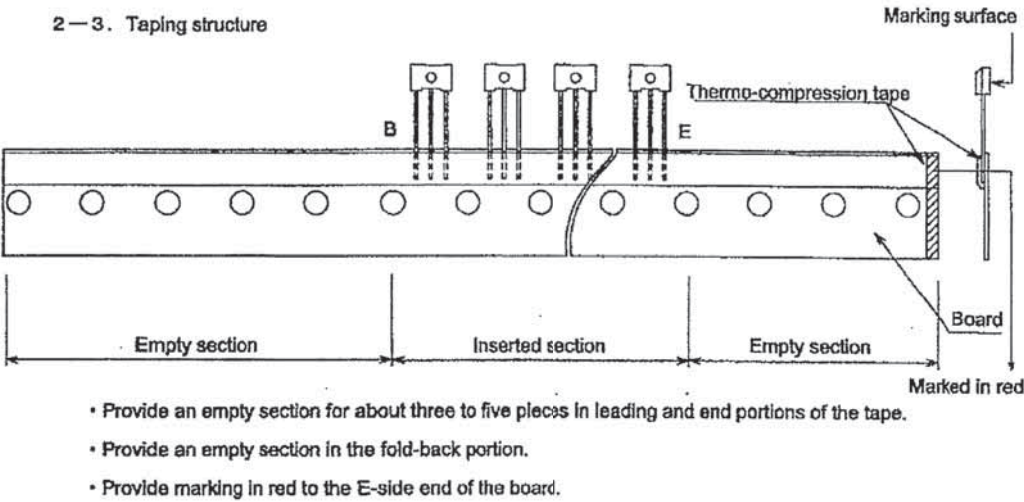


2—2. Taping size standard

Item	Symbol	Standard	Tolerance
Work piece outside diameter	D	6.9	±0.2
	E	2.5	±0.2
Work piece height	A	4.5	±0.2
Lead wire diameter	d	0.5	±0.1
Lead wire thickness	d1	0.45	±0.1
Bonded lead wire	I1	3.0MIN	
Pitch between products	P	12.7	±0.5
Pitch between perforations	P0	12.7	±0.2
Total pitch for 21 perforations	P0×20	254.0	±1.0
Distance between lead wire	F	5.0	+0.8 -0.2
Lead wire pitch distance	F1	2.54	+0.4 -0.1
Displacement of perforations	P1	3.81	±0.3
	P2	6.35	±0.3
Displacement of tape	W2	0~0.5	

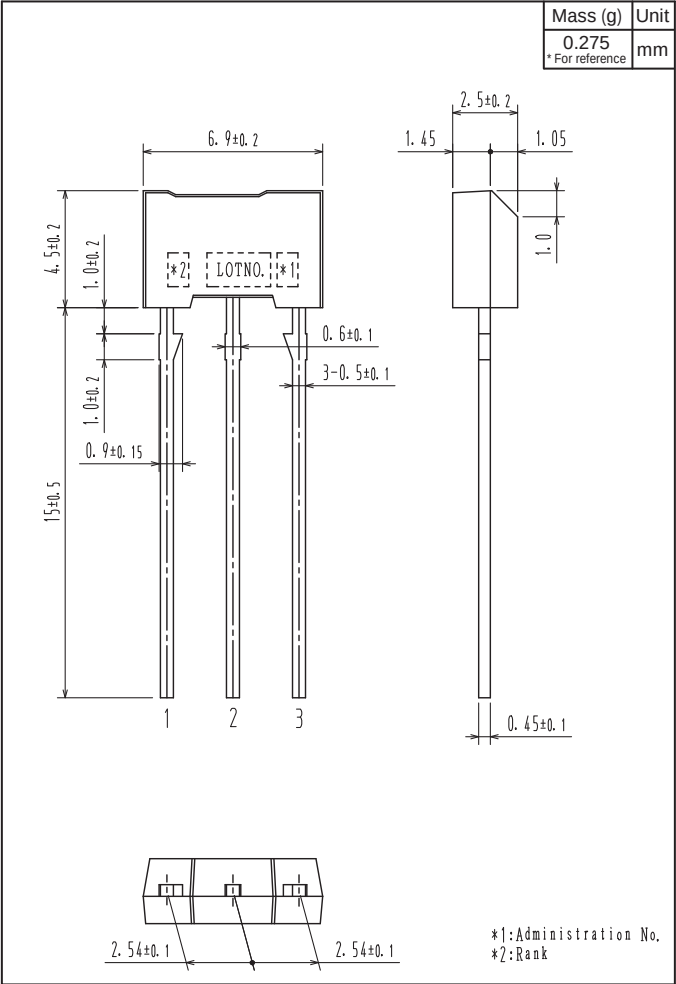
Unit:mm

Item	Symbol	Standard	Tolerance
Tape width	W	18.0	±0.5
Adhesive tape	W0	6.0	±0.5
Displacement of perforations	W1	9.0	±0.5
Work piece bottom surface position	H	19.0	+1.0 -0.5
Work piece upper limit position	H1	23.5	±1.0
Perforations diameter	D0	φ4.0	±0.2
Tape thickness (total thickness)	t	0.6	±0.2
Product inclination	Δc	0	±0.7
Product inclination	Δh	0	±1.0



Outline Drawing

2SA1709S-AN, 2SA1709T-AN, 2SC4489S-AN, 2SC4489T-AN



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